Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3050	solder near (bump or sphere or preform) and (solder or bump or ball) near (first or second or low or lower or high or higher or "lmp" or "lmt" or "hmt" or "hmp")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:33
L2	1617	1 and (solder or bump or ball) near (low or lower or high or higher or "lmp" or "lmt" or "hmt" or "hmp")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:26
L3	234	2 and (solder) near ((low or lower or high or higher) near (temp or temperature) or "lmp" or "lmt" or "hmt" or "hmp")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:26
L4	123	3 and (solder or bump or ball) near (sn or tin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:26
L5	55	4 and eutectic near (sn or tin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:27
L6	28	3 and (heat$4 or reflow$4) near (solder or bump or ball) near (first or second or low or lower or high or higher or "lmp" or "lmt" or "hmt" or "hmp")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:34
L7	11	6 and (heat$4 or reflow$4 or melt$4) near (solder or bump or ball) near (first or second)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:35
L8	211	3 and (semiconductor or chip or die or "ic" or integrated adj circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:35

L9	90	8 and bond$4 near pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:36
L10	7	9 and wire near bond$4 near pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/18 17:36